

## 具有 SNRBoost 功能的双通道 IF 接收器<sup>3G+</sup> 信号处理

查询样品: [ADS58C20](#), [ADS58C23](#)

### 特性

- 差分模拟 IF 输入, DDR LVDS 数字 IF 输出
- 每个接收器具有高达 125-MHz 的信号带宽
  - 采用 40 MHz 和 75 MHz 优化频段
- 高动态性能
- 高阻抗输入
- 80 引脚 TQFP 封装, 具有 PowerPAD™

### 应用

- **ADS58C20:** 多载波 GSM/3G/LTE/TDS-CDMA 蜂窝基站接收器
- **ADS58C23:** 多载波 3G/LTE/TDS-CDMA 蜂窝基站接收器

### 说明

ADS58C20 和 ADS58C23 是适用于宽带、多模式蜂窝基础设施基站的双通道 IF 接收器。每个通道可提供高达 125 MHz 带宽的高动态性能, 并采用 40 MHz 及 75 MHz 的优化频段。IF 接收器架构简化了针对大带宽接收器的前端滤波器设计。接收器在其模拟输入端上内置了集成型缓冲器, 并具有跨宽频率范围的恒量性能和输入阻抗优势。

ADS58C20 是一款拥有出色规格指标的高性能器件, 适合于单模式/多模式蜂窝基站接收机 (包括多载波 GSM)。另外, 该器件还能处理其他的蜂窝协议, 如 TDS-CDMA/3G/LTE 及前一代的系统。

ADS58C23 提供了与 ADS58C20 相同的功能与引出脚配置, 但最小性能指标有所下降, 旨在满足成本和性能较低的系统, 如 TDS-CDMA/3G/LTE 单模式/多模式接收机 (当不需要 GSM 时)。此外, 它还能处理前一代的协议。

这些器件采用 80 引脚 TQFP 封装, 而且其技术规格是针对完整的工业温度范围 (–40°C 至 85°C) 拟订的。



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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English Data Sheet: [SLAS783](#)

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
ADS58C20IPFP	ACTIVE	HTQFP	PFP	80	96	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
ADS58C20IPFPR	ACTIVE	HTQFP	PFP	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
ADS58C23IPFP	ACTIVE	HTQFP	PFP	80	96	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
ADS58C23IPFPR	ACTIVE	HTQFP	PFP	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

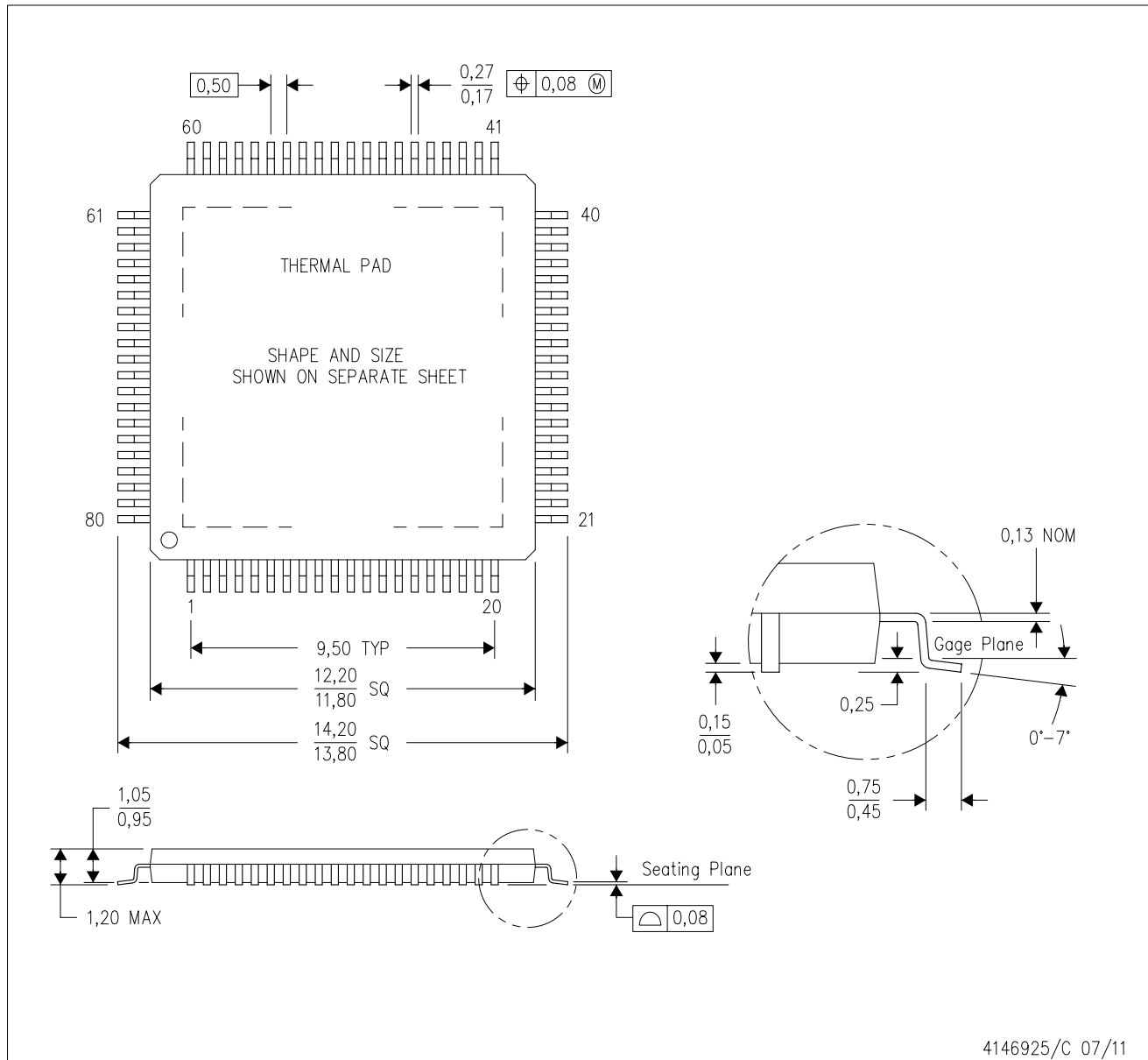
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# MECHANICAL DATA

PFP (S-PQFP-G80)

PowerPAD™ PLASTIC QUAD FLATPACK



4146925/C 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion
  - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - F. Falls within JEDEC MS-026

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## THERMAL PAD MECHANICAL DATA

PFP (S-PQFP-G80)

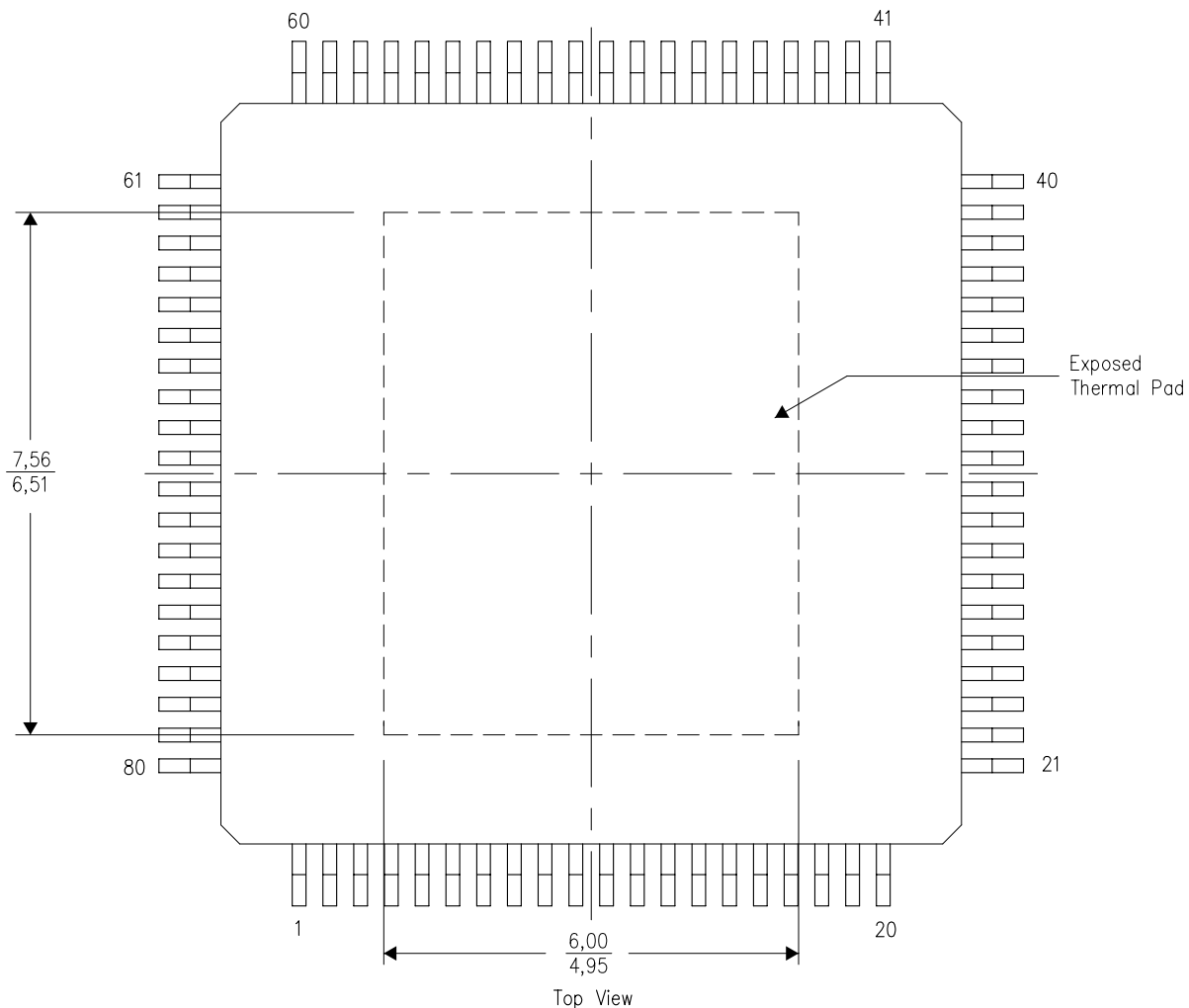
PowerPAD™ PLASTIC QUAD FLATPACK

### THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



4206327-14/N 09/11

NOTE: A. All linear dimensions are in millimeters

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放大器和线性器件	<a href="http://www.ti.com.cn/amplifiers">http://www.ti.com.cn/amplifiers</a>	计算机及周边	<a href="http://www.ti.com.cn/computer">www.ti.com.cn/computer</a>
数据转换器	<a href="http://www.ti.com.cn/dataconverters">http://www.ti.com.cn/dataconverters</a>	消费电子	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
DLP® 产品	<a href="http://www.dlp.com">www.dlp.com</a>	能源	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
DSP - 数字信号处理器	<a href="http://www.ti.com.cn/dsp">http://www.ti.com.cn/dsp</a>	工业应用	<a href="http://www.ti.com.cn/industrial">www.ti.com.cn/industrial</a>
时钟和计时器	<a href="http://www.ti.com.cn/clockandtimers">http://www.ti.com.cn/clockandtimers</a>	医疗电子	<a href="http://www.ti.com.cn/medical">www.ti.com.cn/medical</a>
接口	<a href="http://www.ti.com.cn/interface">http://www.ti.com.cn/interface</a>	安防应用	<a href="http://www.ti.com.cn/security">www.ti.com.cn/security</a>
逻辑	<a href="http://www.ti.com.cn/logic">http://www.ti.com.cn/logic</a>	汽车电子	<a href="http://www.ti.com.cn/automotive">www.ti.com.cn/automotive</a>
电源管理	<a href="http://www.ti.com.cn/power">http://www.ti.com.cn/power</a>	视频和影像	<a href="http://www.ti.com.cn/video">www.ti.com.cn/video</a>
微控制器 (MCU)	<a href="http://www.ti.com.cn/microcontrollers">http://www.ti.com.cn/microcontrollers</a>	无线通信	<a href="http://www.ti.com.cn/wireless">www.ti.com.cn/wireless</a>
RFID 系统	<a href="http://www.ti.com.cn/rfidsys">http://www.ti.com.cn/rfidsys</a>		
RF/IF 和 ZigBee® 解决方案	<a href="http://www.ti.com.cn/radiofre">www.ti.com.cn/radiofre</a>		
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邮寄地址: 上海市浦东新区世纪大道 1568 号, 中建大厦 32 楼 邮政编码: 200122  
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